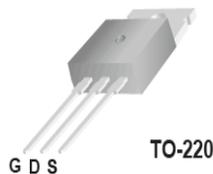


# TSP60R190S1

## 600V 20A N-Channel SJ-MOSFET

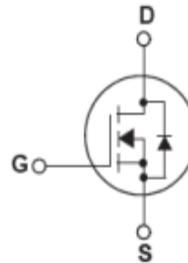
### General Description

Truesemi SJ-FET is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance. This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme  $dv/dt$  rate and higher avalanche energy. SJ-FET is suitable for various AC/DC power conversion in switching mode operation for higher efficiency.



### Features

- 650V @ $T_J = 150^\circ\text{C}$
- Typ.  $R_{DS(on)} = 0.16\Omega$
- Ultra Low gate charge (typ.  $Q_g = 70\text{nC}$ )
- 100% avalanche tested



### Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
$V_{DSS}$	Drain-Source Voltage	600	V
$I_D$	Drain Current -Continuous ( $T_C = 25^\circ\text{C}$ )	20	A
	-Continuous ( $T_C = 100^\circ\text{C}$ )	10	
$I_{DM}$	Drain Current – Pulsed (Note 1)	62	A
$V_{GSS}$	Gate-Source voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	485	mJ
$I_{AR}$	Avalanche Current (Note 1)	20	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	1	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ (Note 3)	4.5	V/ns
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	205	W
	-Derate above $25^\circ\text{C}$	1.67	
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

\* Drain current limited by maximum junction temperature.

### Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.6	$^\circ\text{C/W}$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62	$^\circ\text{C/W}$

## Electrical Characteristics TC = 25 °C unless otherwise noted

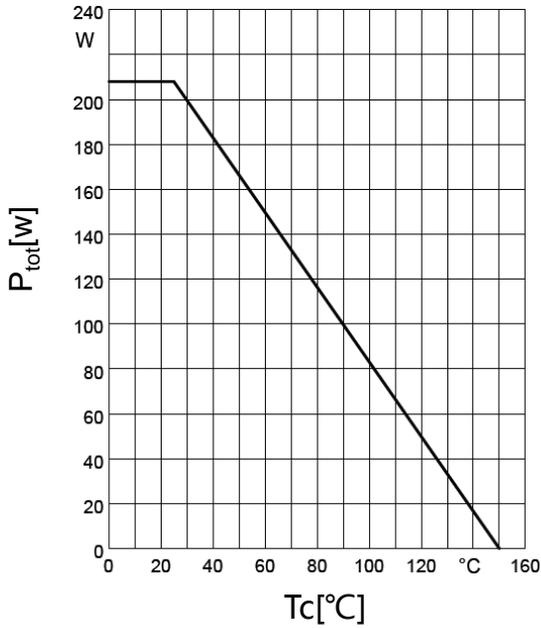
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA, T <sub>J</sub> = 25 °C	600	--	--	V
		V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA, T <sub>J</sub> = 150 °C	--	650	--	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, Referenced to 25 °C	--	0.6	--	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V, T <sub>C</sub> = 25 °C	--	--	1	μA
		V <sub>DS</sub> = 480V, V <sub>GS</sub> = 0V, T <sub>C</sub> = 125 °C	--	10	--	μA
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30V, V <sub>DS</sub> = 0V	--	--	100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30V, V <sub>DS</sub> = 0V	--	--	-100	nA
On Characteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2.5	--	4.5	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 5A	--	0.16	0.19	Ω
g <sub>FS</sub>	Forward Trans conductance	V <sub>DS</sub> = 40V, I <sub>D</sub> = 5A (Note 4)	--	16	--	S
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1.0MHz	--	1440	--	pF
C <sub>oss</sub>	Output Capacitance		--	300	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	10	--	pF
Switching Characteristics						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 400V, I <sub>D</sub> = 5A, R <sub>G</sub> = 20Ω (Note 4, 5)	--	25	--	ns
t <sub>r</sub>	Turn-On Rise Time		--	55	--	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		--	70	--	ns
t <sub>f</sub>	Turn-Off Fall Time		--	40	--	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 480V, I <sub>D</sub> = 10A, V <sub>GS</sub> = 10V (Note 4, 5)	--	70	90	nC
Q <sub>gs</sub>	Gate-Source Charge		--	7.8	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	9	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current		--	--	20	A
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current		--	--	60	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>F</sub> = 10A	--	1	1.5	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0V, I <sub>F</sub> = 10A, di <sub>F</sub> /dt = 100A/μs (Note 4)	--	475	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	5.8	--	μC
I <sub>rrm</sub>	Peak reverse recovery Current				35	--

## NOTES:

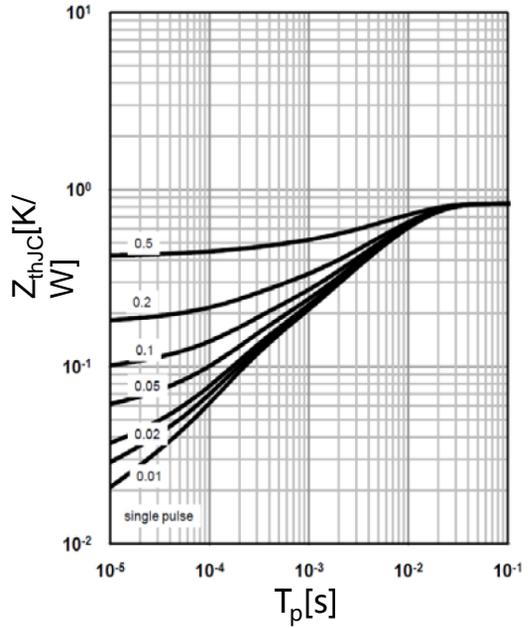
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. L=79mH, I<sub>AS</sub>=3.5A, V<sub>DD</sub>=50V, Starting T<sub>J</sub>=25 °C
3. I<sub>SD</sub>≤20A, di/dt ≤ 200A/μs, V<sub>DD</sub> ≤ BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25 °C
4. Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 2%
5. Essentially Independent of Operating Temperature Typical Characteristics

# Typical Performance Characteristics

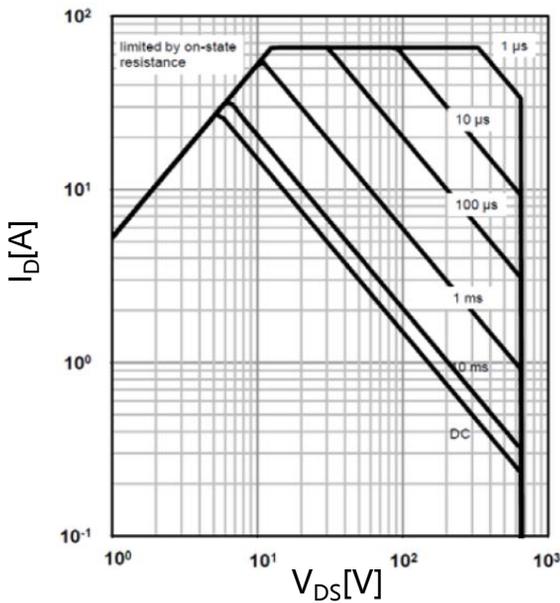
Power dissipation



Max. transient thermal impedance

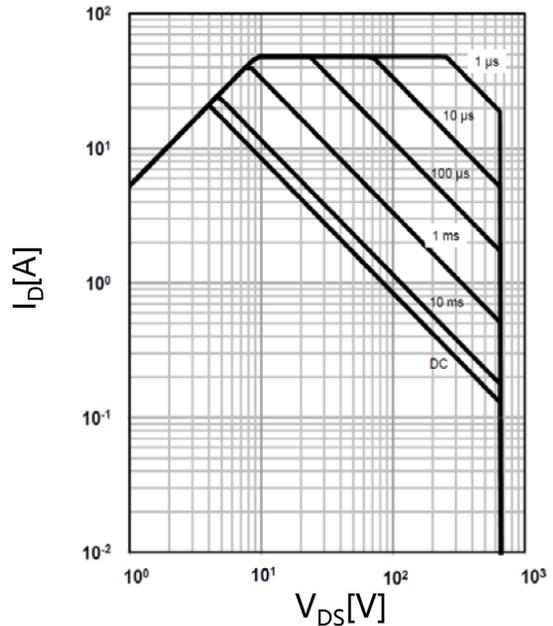


Safe operating area  $T_C=25\text{ }^\circ\text{C}$



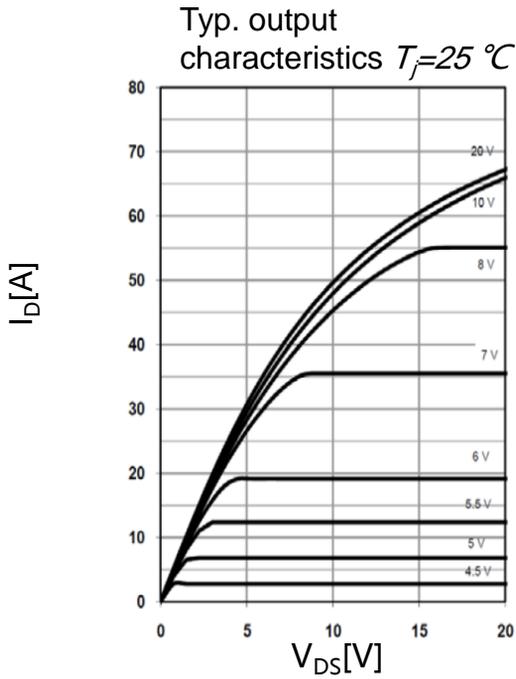
$I_D=f(V_{DS}); T_C=25\text{ }^\circ\text{C}; V_{GS} > 7\text{V};$   
 $D=0;$  parameter  $t_p$

Safe operating area  $T_C=80\text{ }^\circ\text{C}$

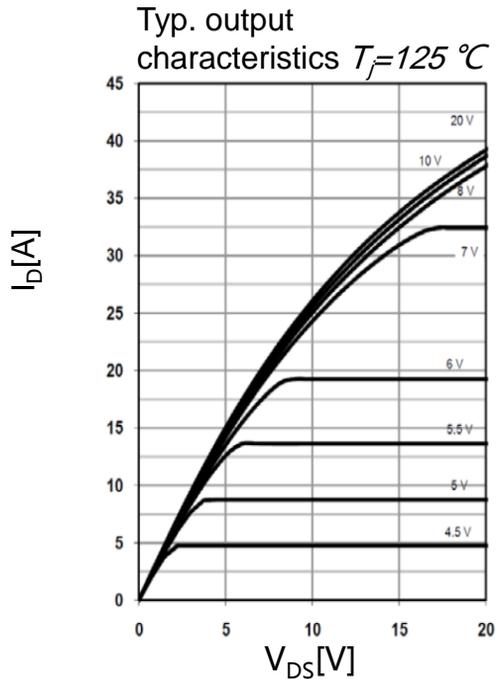


$I_D=f(V_{DS}); T_C=80\text{ }^\circ\text{C}; V_{GS} > 7\text{V};$   
 $D=0;$  parameter  $t_p$

# Typical Performance Characteristics

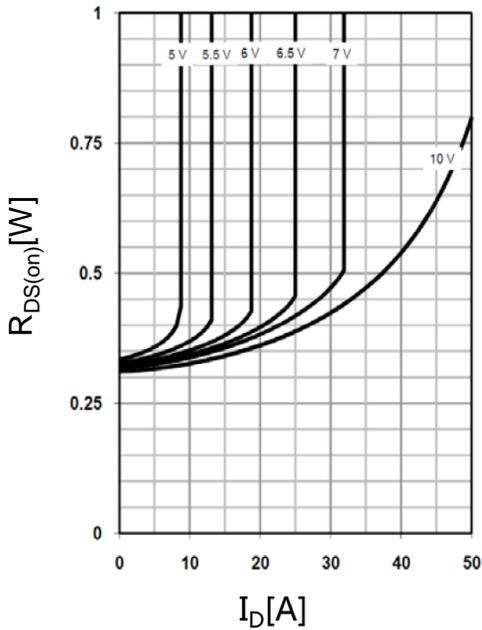


$I_D=f(V_{DS}); T_j=25^\circ\text{C}$  ; parameter:  $V_{GS}$



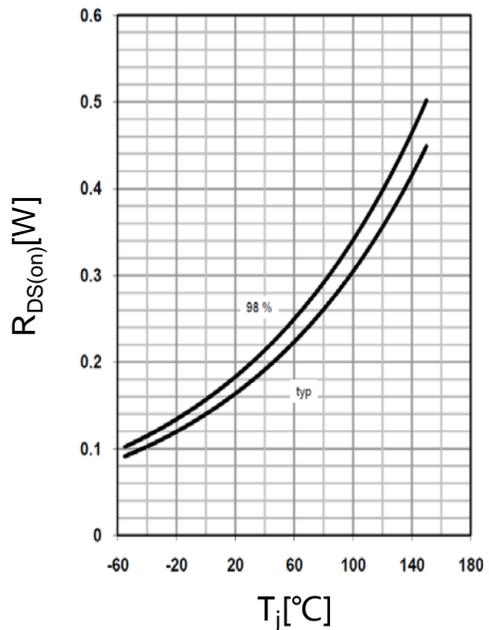
$I_D=f(V_{DS}); T_j=125^\circ\text{C}$  ; parameter:  $V_{GS}$

Typ. drain-source on-state resistance



$R_{DS(on)}=f(I_D); T_j=125^\circ\text{C}$  ;  
parameter:  $V_{GS}$

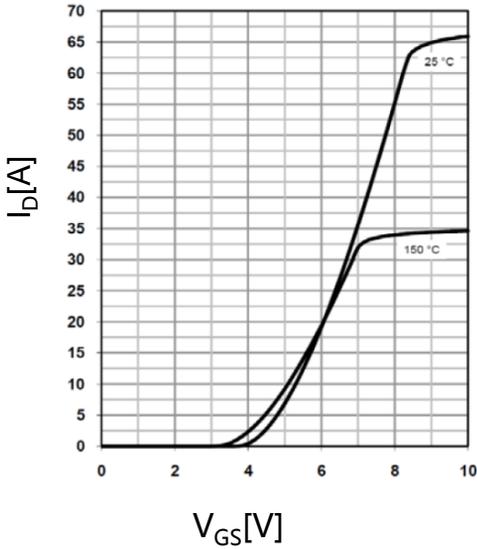
Typ. drain-source on-state resistance



$R_{DS(on)}=f(T_j); I_D=7.3\text{ A}; V_{GS}=10\text{ V}$

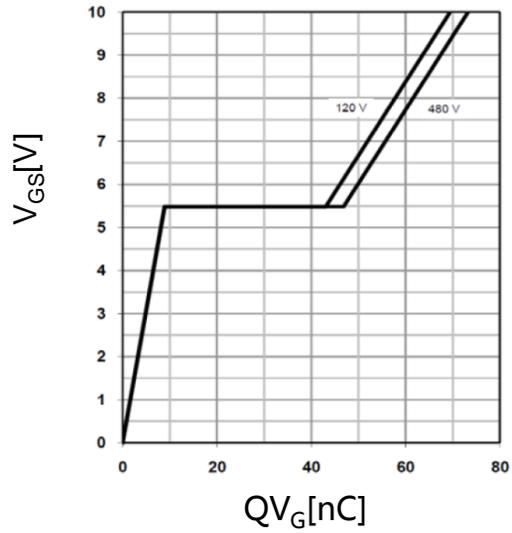
# Typical Performance Characteristics

Typ. transfer characteristics



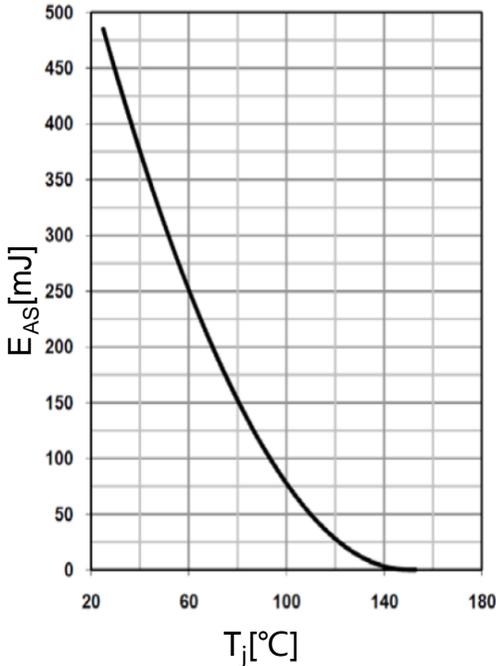
$I_D = f(V_{GS}); V_{DS} = 20V$

Typ. gate charge



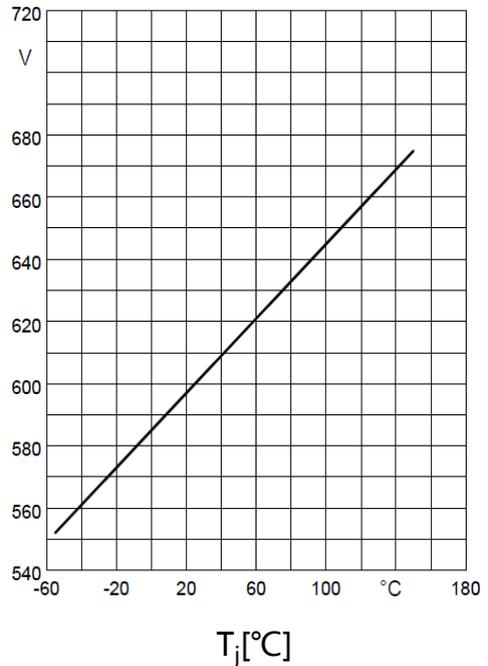
$V_{GS} = f(Q_g), I_D = 11A$  pulsed

Avalanche energy



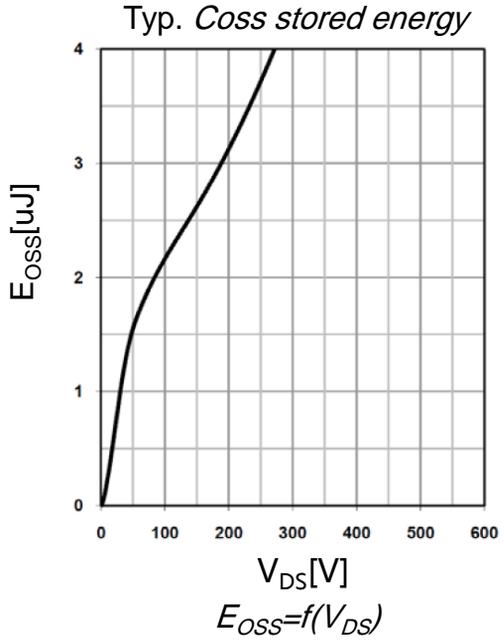
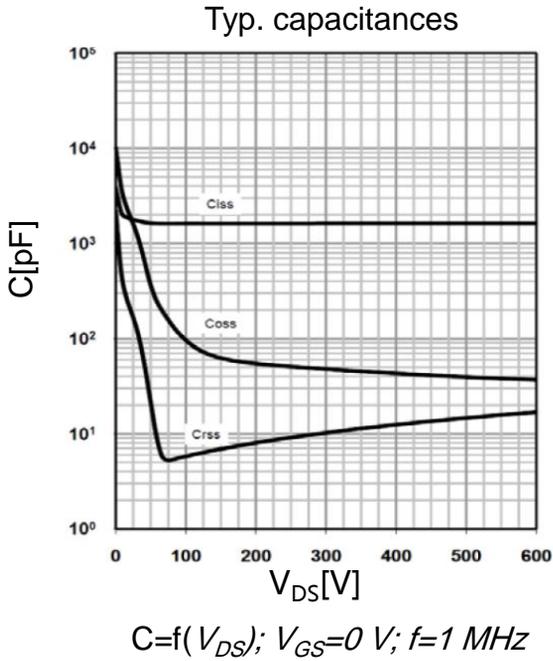
$E_{AS} = f(T_j); I_D = 3.5A; V_{DD} = 50V$

Drain-source breakdown voltage

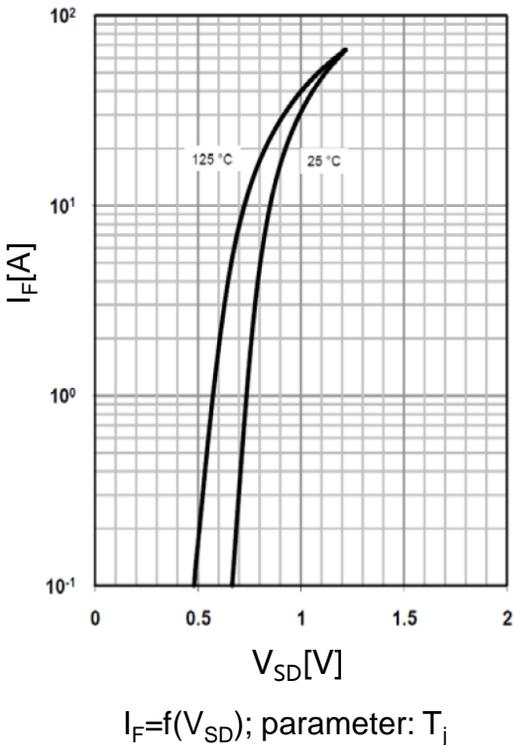


$V_{BR(DSS)} = f(T_j); I_D = 1.0mA$

# Typical Performance Characteristics

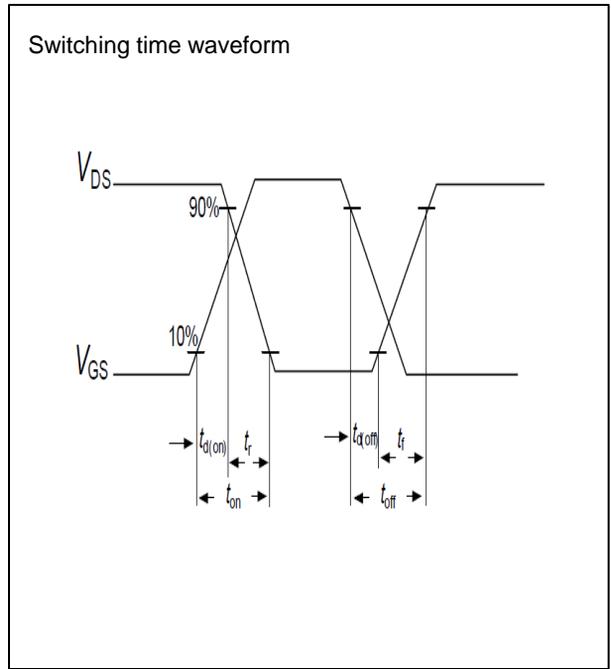
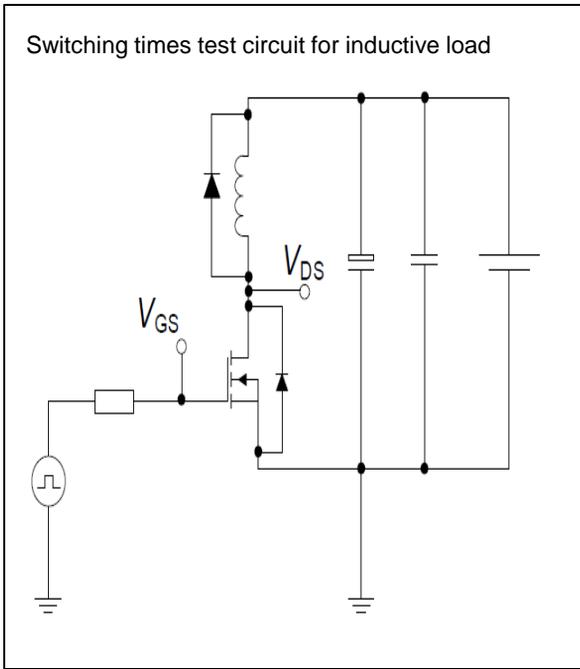


## Forward characteristics of reverse diode

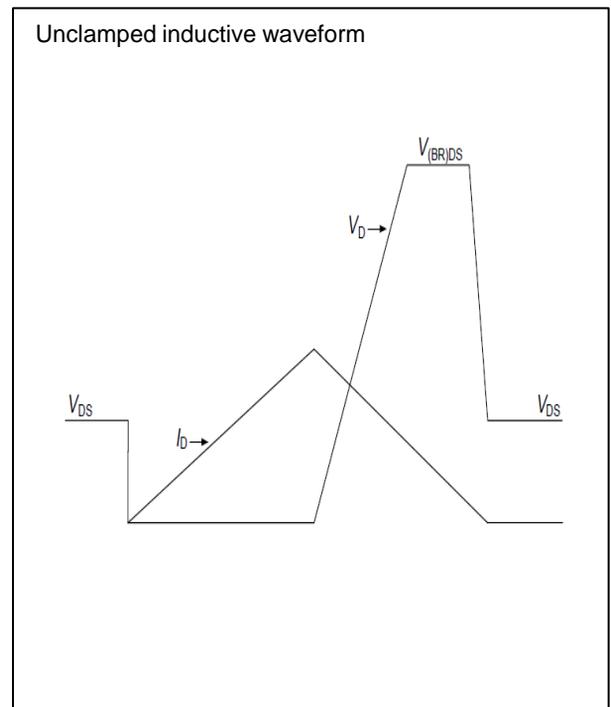
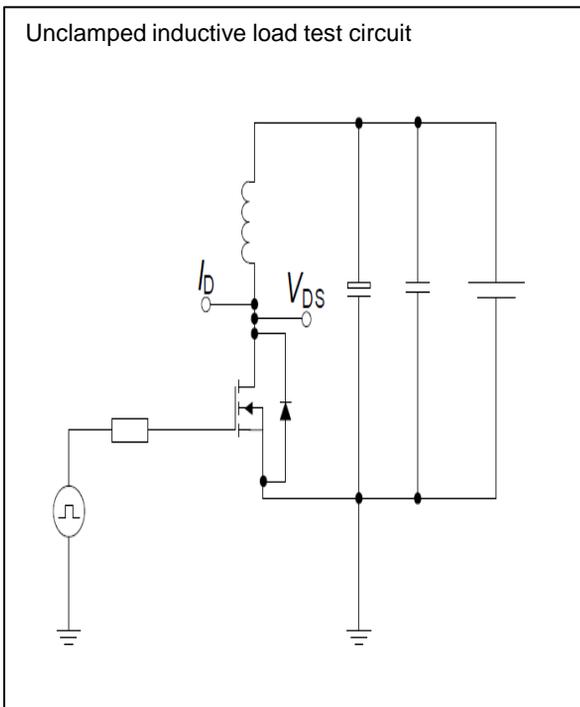


# Test circuits

## Switching times test circuit and waveform for inductive load

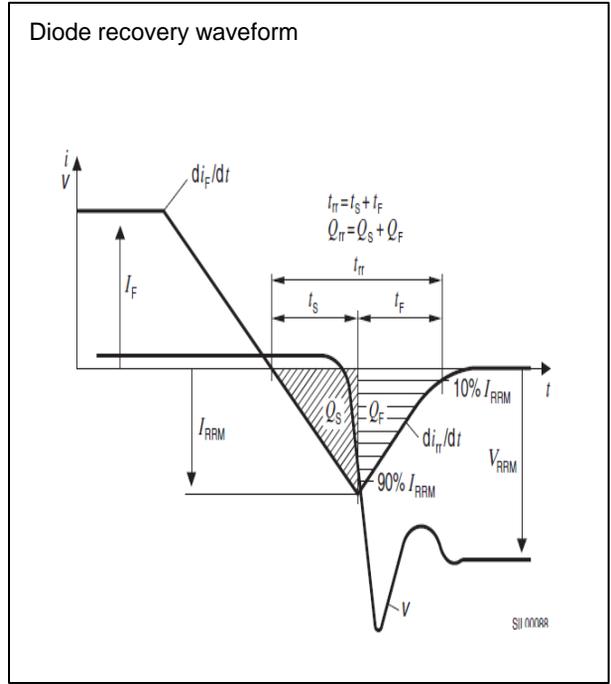
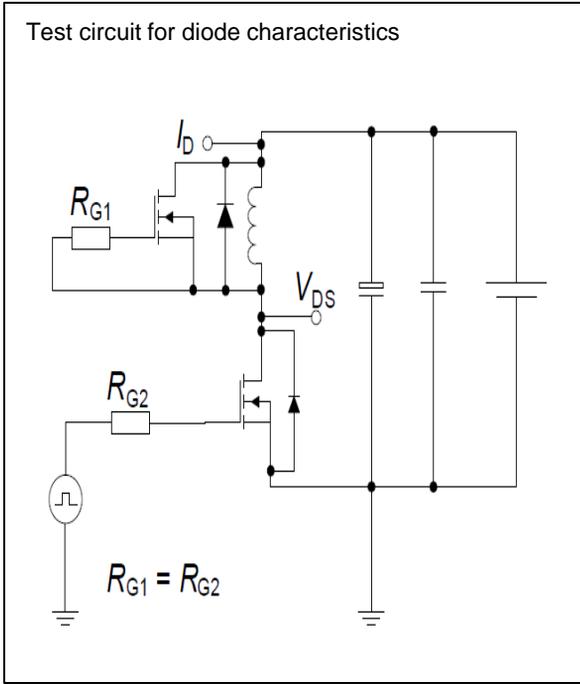


## Unclamped inductive load test circuit and waveform

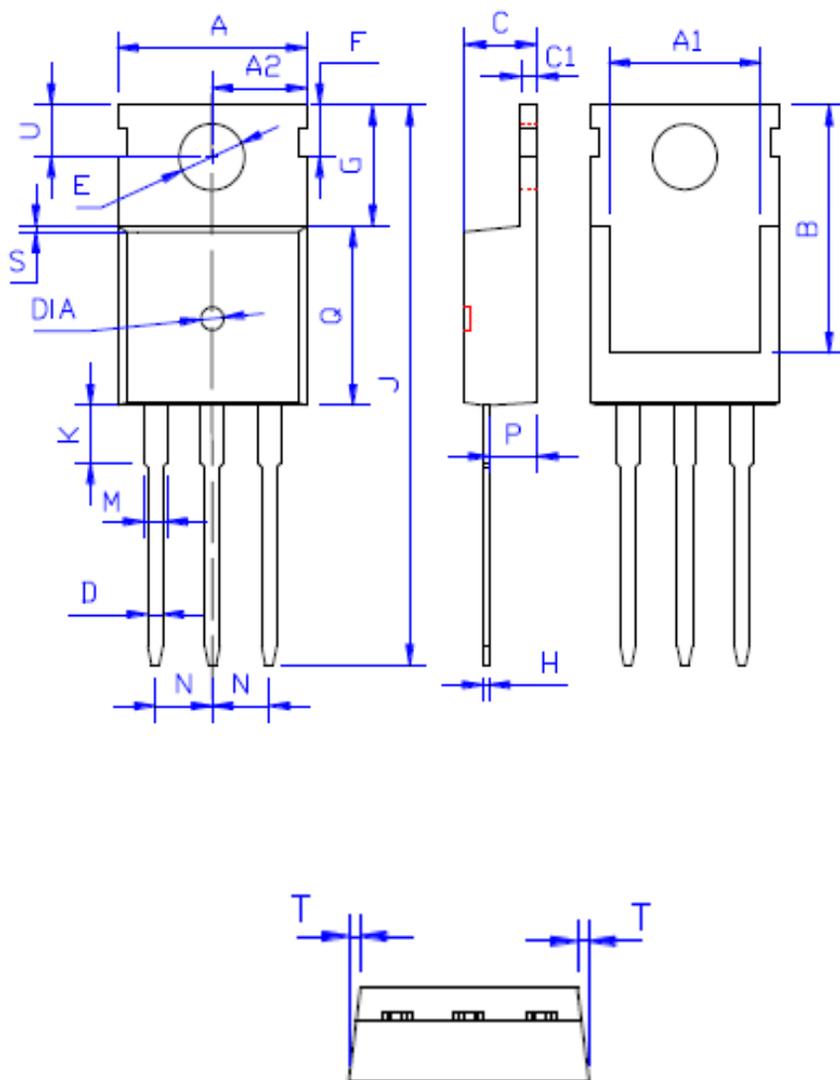


# Test circuits

## Test circuit and waveform for diode characteristics



# Package Outline TO-220



DIM	MILLIMETERS
A	10.00 ± 0.30
A1	8.00 ± 0.30
A2	5.00 ± 0.30
B	13.20 ± 0.40
C	4.50 ± 0.20
C1	1.30 ± 0.20
D	0.80 ± 0.20
E	3.60 ± 0.20
F	3.00 ± 0.30
G	6.60 ± 0.40
H	0.50 ± 0.20
J	28.88 ± 0.50
K	3.00 ± 0.30
M	1.30 ± 0.30
N	Typical 2.54
P	2.40 ± 0.40
Q	9.20 ± 0.40
S	0.25 ± 0.15
T	0.25 ± 0.15
U	2.80 ± 0.30
DIA	宽 1.50 ± 0.10 深 0.50 <b>MAX</b>